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Therefore, all references to "LAPIS Technology Co., Ltd.", "LAPIS Technology"
and/or "LAPIS" in this document shall be replaced with "ROHM Co., Ltd."

Furthermore, there are no changes to the documents relating to our products other than
the company name, the company trademark, logo, etc.

Thank you for your understanding.

ROHM Co., Ltd.
April 1, 2024

MCU Related Document list

Issue date: 17 Apr, 2023

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LAPIS Technology Co.,Ltd.

2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan

<https://www.lapis-tech.com/en/>

1. Introduction

In LAPIS Technology's MCU, some manuals are prepared for other than User's Manual. This document is a list of the documents related to MCU. Read them as necessary.

1.1 Applicable MCU Products

ML62Q2000/2500/2700 group
ML62Q1000 series
ML620Q50x group

2. Related Document list

	Document name	Description
CPU core	nX-U16/100 Core Instruction Manual	Description on the basic architecture and the each instruction of the nX-U16/100 Core.
Assembler	MACU8 Assembler Package User's Manual	Description on the method of operating the relocatable assembler, the linker, the librarian, and the object converter and also on the specifications of the assembler language.
C Compiler	LEXIDE C compiler for U16/U8 User's Manual	Description on the method of operating the LCC-U16 compiler.
	CCU8 User's Manual	Description on the method of operating the compiler.
	CCU8 Programming Guide	Description on the method of programming.
	CCU8 Language Reference	Description on the language specifications.
Library	RTU8 Runtime Library Reference	Description on the RTU8 standard library.
	N-RTU16 Runtime Library Reference	Description on the N-RTU16 standard library.
	MULDIVU8LIB Multiplication and Division Library for U8/U16 Accelerator User's Manual	Description on the MULDIVU8LIB Multiplication and Division Library.
Development Support tools	DTU8 Debugger User's Manual	Description on the method of operating the debugger DTU8.
	LEXIDE-Ω User's Manual	Description on the integrated development environment LEXIDE-Ω.
	EASE1000V2 User's Manual	Description on the on-chip debug emulator EASE1000V2.
	HTU8 User's Manual	Description on the ROM code data generation tool HTU8.
	Multiple Flash Writer MWU16 User's Manual	Description on the Multiple Flash Writer MWU16.
	LCD Image Tool User's Manual	Description on the method of operating the LCD Image Tool.

3. Revision History

Document No.	Issue date	Page		Description
		Previous Rev.	Update Rev.	
FEXL_MCU_RELDLIST-01	2020.01.24	-	-	First Revision
FEXL_MCU_RELDLIST-02	2022.04.12	1	1	Updated note.
		2	2	Added applicable products Deleted IDEU8
FEXL_MCU_RELDLIST-03	2023.04.17	2	2	Added applicable products, LEXIDE C compiler, standard library, LCD image tool Updated the integrated development tool